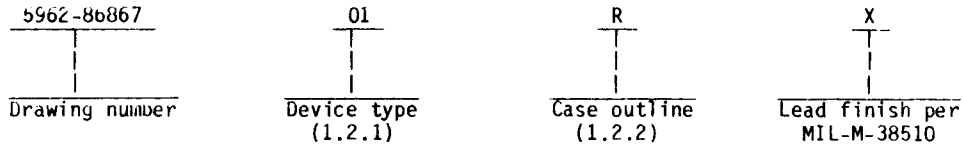


1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device type. The device type shall identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	54HCT373	Octal three-state transparent latch with TTL compatible inputs

1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

<u>Outline letter</u>	<u>Case outline</u>
R	D-8 (20-lead, 1.060" x .310" x .200"), dual-in-line package
S	F-9 (20-lead, .540" x .300" x .100"), flat package
2	C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package

1.3 Absolute maximum ratings. 1/

Supply voltage range - - - - -	-0.5 V dc to +7.0 V dc
DC input voltage - - - - -	-0.5 V dc to $V_{CC} + 0.5$ V dc
DC output voltage - - - - -	-0.5 V dc to $V_{CC} + 0.5$ V dc
Clamp diode current (I_{IK}, I_{OK}) - - - - -	± 20 mA
DC output current (per pin) - - - - -	± 35 mA
DC V_{CC} or GND current (per pin) - - - - -	± 70 mA
Storage temperature range - - - - -	-65°C to +150°C
Maximum power dissipation (P_D) - - - - -	500 mW 2/
Lead temperature (soldering, 10 seconds) - -	+300°C
Thermal resistance, junction-to-case (θ_{JC}) -	See MIL-M-38510, appendix C
Junction temperature (T_J) - - - - -	+175°C

1.4 Recommended operating conditions.

Supply voltage (V_{CC}) - - - - -	+4.5 V dc to +5.5 V dc
Input voltage (V_{IN}) - - - - -	0 V dc to V_{CC}
Output voltage (V_{OUT}) - - - - -	0 V dc to V_{CC}
Case operating temperature (T_C) - - - - -	-55°C to +125°C
Input rise or fall time, $V_{CC} = 4.5$ V - - - -	0 to 500 ns

1/ Unless otherwise specified, all voltages are referenced to ground.

2/ For $T_C = +100^\circ\text{C}$ to +125°C, derate linearly at 12 mW/°C.

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Minimum setup time, Data to LATCH ENABLE (t_s):

$T_C = +25^\circ\text{C}$, $V_{CC} = 4.5\text{ V}$ - - - - -	20 ns
$T_C = -55^\circ\text{C}$ to $+125^\circ\text{C}$, $V_{CC} = 4.5\text{ V}$ - - - - -	30 ns

Minimum LATCH ENABLE pulse width (t_w):

$T_C = +25^\circ\text{C}$, $V_{CC} = 4.5\text{ V}$ - - - - -	20 ns
$T_C = -55^\circ\text{C}$ to $+125^\circ\text{C}$, $V_{CC} = 4.5\text{ V}$ - - - - -	30 ns

Minimum hold time, Data to LATCH ENABLE (t_h):

$T_C = +25^\circ\text{C}$, $V_{CC} = 4.5\text{ V}$ - - - - -	10 ns
$T_C = -55^\circ\text{C}$ to $+125^\circ\text{C}$, $V_{CC} = 4.5\text{ V}$ - - - - -	20 ns

2. APPLICABLE DOCUMENTS

2.1 Government specification, standard, and bulletin. Unless otherwise specified, the following specification, standard, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standard, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth table. The truth table shall be as specified on figure 2.

3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C < T _C < +125°C 1/ unless otherwise specified	Group A subgroups	Limits		Unit
				Min	Max	
High level output voltage	V _{OH}	V _{CC} = 4.5 V; V _{IN} = 2.0 V or 0.8 V	I _O = 20 μA	1, 2, 3	4.4	V
					I _O = 6.0 mA	
Low level output voltage	V _{OL}	V _{CC} = 4.5 V; V _{IN} = 2.0 V or 0.8 V	I _O = 20 μA	1, 2, 3	0.1	V
					I _O = 6.0 mA	
High level input voltage	V _{IH}	V _{CC} = 4.5 V 2/	1, 2, 3	2.0	V	
Low level input voltage	V _{IL}	V _{CC} = 4.5 V 2/	1, 2, 3	0.8	V	
Input capacitance	C _{IN}	V _{CC} = GND, T _C = +25°C, see 4.3.1c	4	10	pF	
Output capacitance	C _{OUT}	T _C = +25°C, see 4.3.1c	4	20	pF	
Quiescent current	I _{CC}	V _{CC} = 5.5 V; V _{IN} = V _{CC} or GND I _{OUT} = 0.0 A	1, 2, 3	160	μA	
Input leakage current	I _{IN}	V _{CC} = 5.5 V; V _{IN} = V _{CC} or GND	1, 2, 3	±1.0	μA	
Functional tests		See 4.3.1d	7, 8			
Three-state output current	I _{OZ}	V _{CC} = 5.5 V V _{IN} = 2.0 V or 0.8 V, V _O = V _{CC} or GND	1, 2, 3	±10	μA	
Additional quiescent supply current	ΔI _{CC}	Any 1 input: V _{IN} = 2.4 V or 0.5 V Other inputs: V _{IN} = V _{CC} or GND I _{OUT} = 0.0 A V _{CC} = 5.5 V	1, 2, 3	3.0	mA	

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C < T _C < +125°C 1/ unless otherwise specified	Group A subgroups	Limits		Unit
				Min	Max	
Propagation delay, D to Q	t _{PHL1} , t _{PLH1}	V _{CC} = 5.0 V, C _L = 50 pF, See figure 4	9		35	ns
			10, 11		53	ns
Propagation delay, output disable time, OUTPUT ENABLE to Q	t _{PLZ} , t _{PHZ}		9		35	ns
			10, 11		53	ns
Propagation delay, output enable time, OUTPUT ENABLE to Q	t _{PZL} , t _{PZH}		9		35	ns
			10, 11		53	ns
Propagation delay, LATCH ENABLE to Q	t _{PHL2} , t _{PLH2}		9		35	ns
			10, 11		53	ns
Transition time <u>3/</u>	t _{TLH} , t _{THL}		9		12	ns
			10, 11		18	ns

- 1/ For a power supply of 5 V ±10 percent, the worst case output voltages (V_{OH} and V_{OL}) occur for HCT at 4.5 V. Thus, the 4.5 V values should be used when designing with this supply. Worst cases V_{IH} and V_{IL} occur at V_{CC} = 5.5 V and 4.5 V respectively.
- 2/ V_{IH} and V_{IL} are not required and shall be applied as forcing functions for V_{OH} or V_{OL} tests.
- 3/ Transition time (t_{TLH}, t_{THL}), if not tested, shall be guaranteed to the specified limits.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-ECC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

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Device type	01
Case outlines	R, S, and 2
Terminal number	Terminal symbol
1	OUTPUT ENABLE
2	Q0
3	D0
4	D1
5	Q1
6	Q2
7	D2
8	D3
9	Q3
10	GND
11	LATCH ENABLE
12	Q4
13	D4
14	D5
15	Q5
16	Q6
17	D6
18	D7
19	Q7
20	V _{CC}

FIGURE 1. Terminal connections.

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OUTPUT ENABLE	LATCH ENABLE	Data	Output
L	H	H	H
L	H	L	L
L	L	X	Q ₀
H	X	X	Z

H = High level, L = Low level
 Q₀ = Level of output before steady-state input conditions were established
 Z = High impedance

FIGURE 2. Truth table.

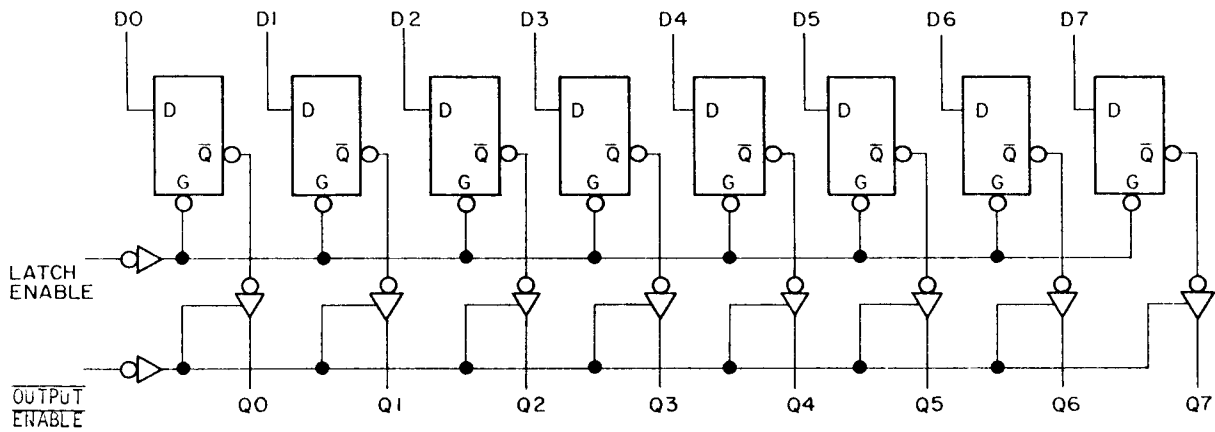


FIGURE 3. Logic diagram.

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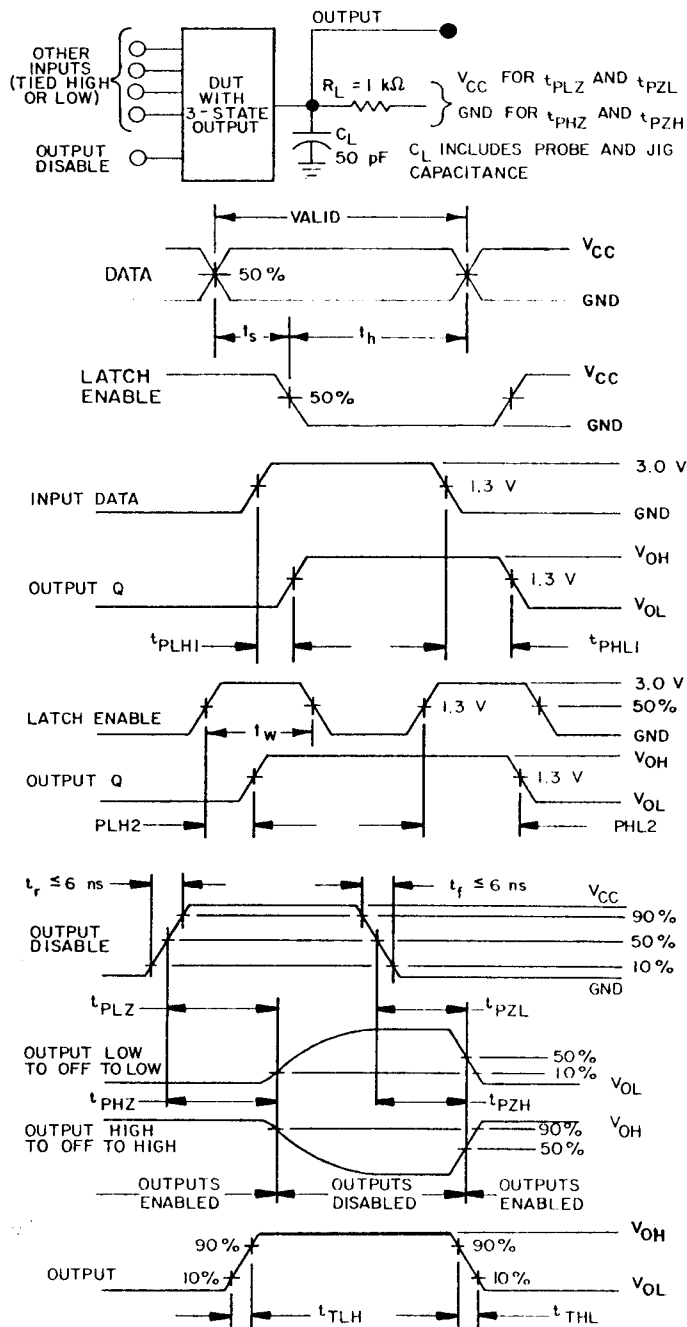


FIGURE 4. Switching waveforms and test circuit.

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3.8 Notification of change. Notification of change to DESC-ECC shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.9 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125^\circ\text{C}$, minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

** Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

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4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 (C_{IN} and C_{OUT} measurements) shall be measured only for the initial test and after process or design changes which may affect capacitance. Capacitance shall be measured between the designated terminal and GND at a frequency of 1 MHz. Test all applicable pins on five devices with zero failures.
- d. Subgroups 7 and 8 tests shall verify the truth table as specified on figure 2.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125^\circ\text{C}$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).

6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-ECS, telephone (513) 296-6022.

6.5 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone (513) 296-5375.

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o.6 Approved sources of supply. Approved sources of supply are listed in MIL-BUL-103. Additional sources will be added to MIL-BUL-103 as they become available. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECS. The approved sources listed below are for information purposes only and are current only to the date of the last action of this document.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1/</u>
5962-8686701RX	01295 34371 27014	SNJ54HCT373J CD54HCT373F/3A MM54HCT373J/883
5962-8686701SX	27014	MM54HCT373W/883
5962-86867012X	01295 27014	SNJ54HCT373FK MM54HCT373E/883

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements

<u>Vendor CAGE number</u>	<u>Vendor name and address</u>
01295	Texas Instruments, Incorporated 13500 North Central Expressway P.O. Box 655303 Dallas TX 75265 Point of contact: I-20 at FM 1788 Midland, TX 79711-0448
27014	National Semiconductor 2900 Semiconductor Drive P.O. Box 58090 Santa Clara, CA 95052-8090 Point of contact: 333 Western Avenue South Portland, ME 04106
34371	Harris Semiconductor P.O. Box 883 Melbourne, FL 32901

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